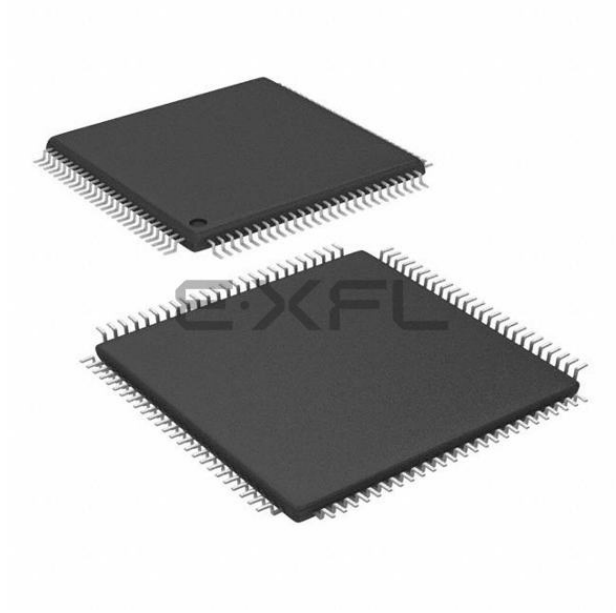
Microchip Technology - DSPIC33FJ256GP510AT-I/PF Datasheet



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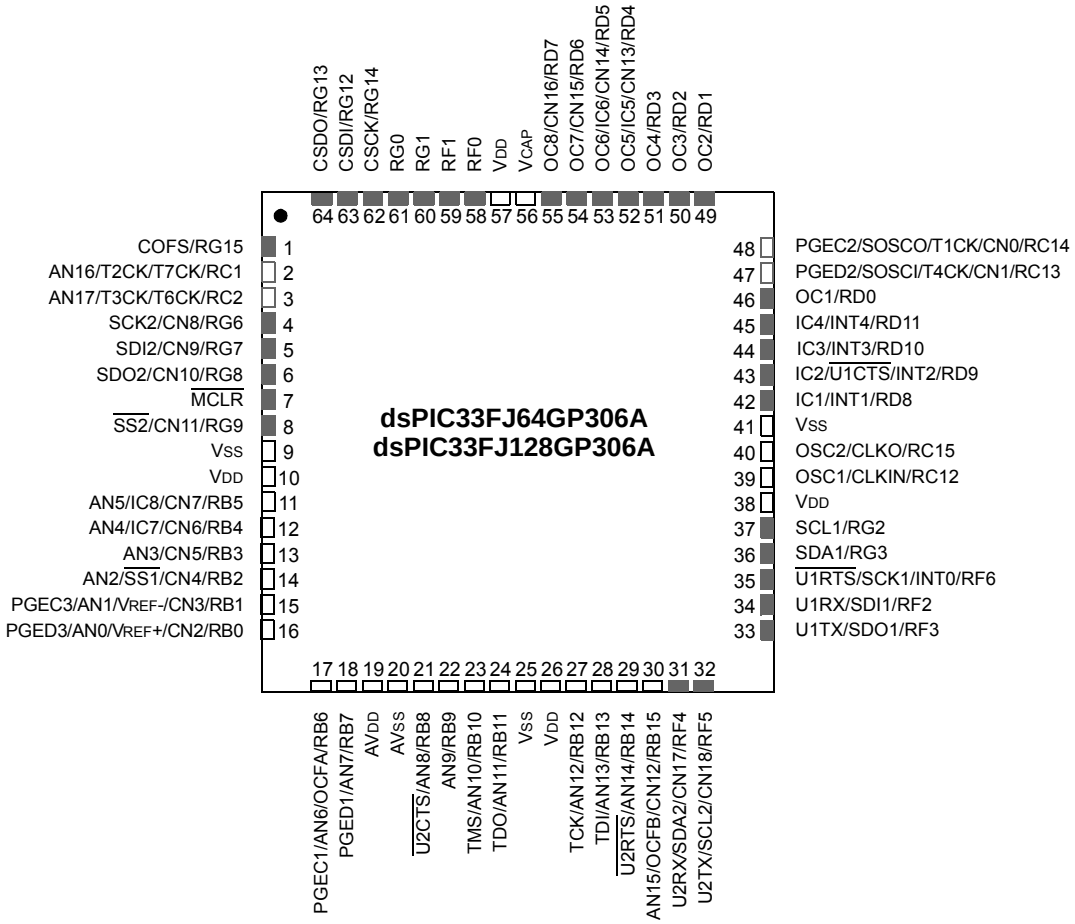
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	CANbus, I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	AC'97, Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	85
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 32x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33fj256gp510at-i-pf

Pin Diagrams (Continued)

64-Pin QFN(1)

■ = Pins are up to 5V tolerant

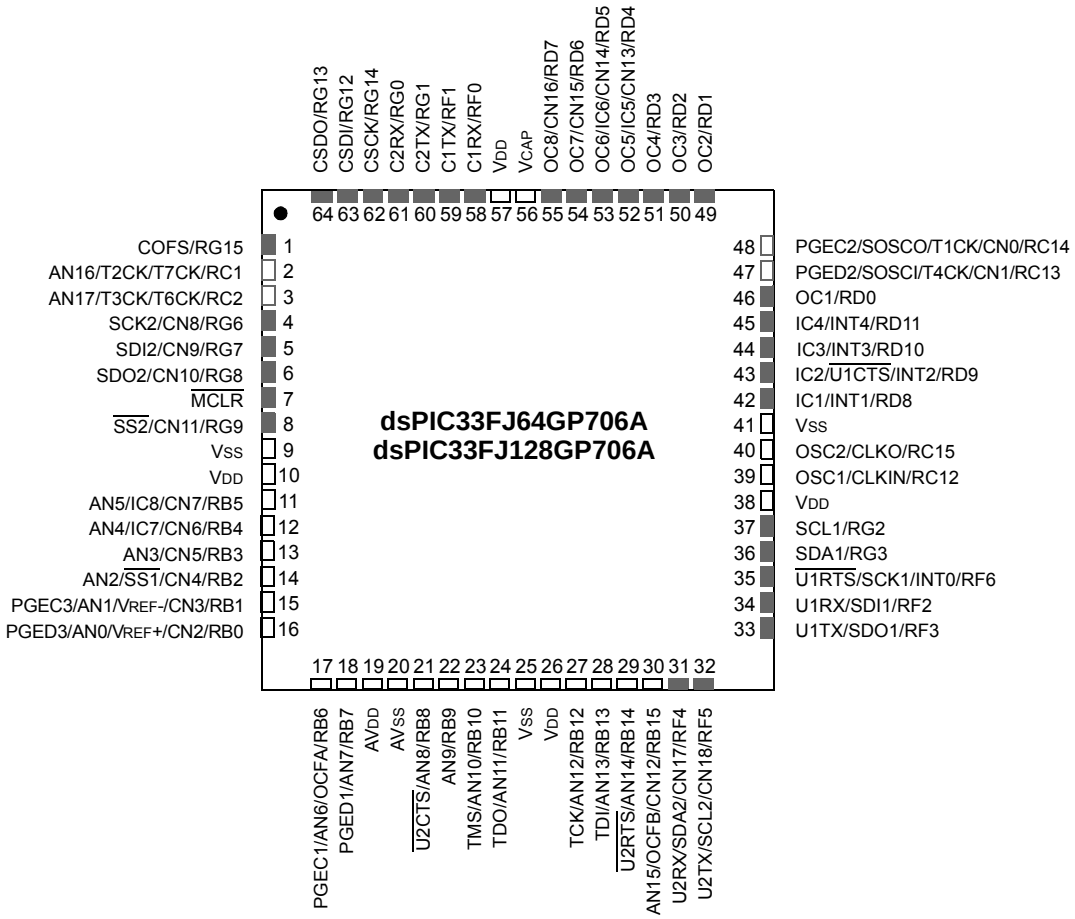


Note 1: The metal plane at the bottom of the device is not connected to any pins and should be connected to VSS externally.

Pin Diagrams (Continued)

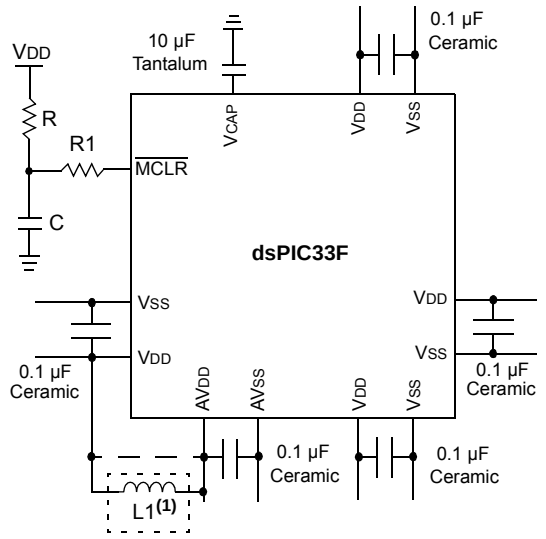
64-Pin QFN(1)

■ = Pins are up to 5V tolerant



Note 1: The metal plane at the bottom of the device is not connected to any pins and should be connected to VSS externally.

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



Note 1: As an option, instead of a hard-wired connection, an inductor (L1) can be substituted between VDD and AVDD to improve ADC noise rejection. The inductor impedance should be less than 1Ω and the inductor capacity greater than 10 mA.

Where:

$$f = \frac{F_{CNV}}{2}$$ (i.e., ADC conversion rate/2)

$$f = \frac{1}{(2\pi\sqrt{LC})}$$

$$L = \left(\frac{1}{(2\pi f\sqrt{C})}\right)^2$$

2.2.1 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits including DSCs to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

2.3 CPU Logic Filter Capacitor Connection (VCAP)

A low-ESR (< 5 Ohms) capacitor is required on the VCAP pin, which is used to stabilize the voltage regulator output voltage. The VCAP pin must not be connected to VDD, and must have a capacitor between 4.7 µF and 10 µF, 16V connected to ground. The type can be ceramic or tantalum. Refer to **Section 25.0 "Electrical Characteristics"** for additional information.

The placement of this capacitor should be close to the VCAP. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 22.2 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides for two specific device functions:

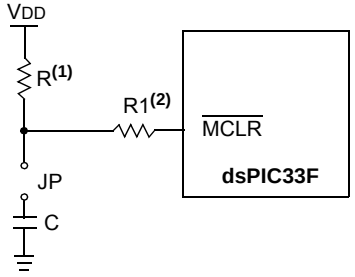
- Device Reset
- Device programming and debugging

During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as shown in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2: EXAMPLE OF MCLR PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the MCLR pin VIH and VIL specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.

TABLE 4-20: ECAN1 REGISTER MAP WHEN C1CTRL1.WIN = 1 FOR dsPIC33FJXXXGP506A/510A/706A/708A/710A DEVICES ONLY

File Name	Addr	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
C1RXF11SID	046C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF11EID	046E	EID<15:8>								EID<7:0>								xxxx
C1RXF12SID	0470	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF12EID	0472	EID<15:8>								EID<7:0>								xxxx
C1RXF13SID	0474	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF13EID	0476	EID<15:8>								EID<7:0>								xxxx
C1RXF14SID	0478	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF14EID	047A	EID<15:8>								EID<7:0>								xxxx
C1RXF15SID	047C	SID<10:3>								SID<2:0>			—	EXIDE	—	EID<17:16>		xxxx
C1RXF15EID	047E	EID<15:8>								EID<7:0>								xxxx

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

TABLE 6-3: RESET DELAY TIMES FOR VARIOUS DEVICE RESETS

Reset Type	Clock Source	$\overline{\text{SYSRST}}$ Delay	System Clock Delay	FSCM Delay	See Notes
POR	EC, FRC, LPRC	TPOR + TSTARTUP + TRST	—	—	**1, 2, 3**
	ECPLL, FRCPLL	TPOR + TSTARTUP + TRST	TLOCK	TFSCM	**1, 2, 3, 5, 6**
	XT, HS, SOSC	TPOR + TSTARTUP + TRST	TOST	TFSCM	**1, 2, 3, 4, 6**
	XTPLL, HSPLL	TPOR + TSTARTUP + TRST	TOST + TLOCK	TFSCM	**1, 2, 3, 4, 5, 6**
BOR	EC, FRC, LPRC	TSTARTUP + TRST	—	—	**3**
	ECPLL, FRCPLL	TSTARTUP + TRST	TLOCK	TFSCM	**3, 5, 6**
	XT, HS, SOSC	TSTARTUP + TRST	TOST	TFSCM	**3, 4, 6**
	XTPLL, HSPLL	TSTARTUP + TRST	TOST + TLOCK	TFSCM	**3, 4, 5, 6**
$\overline{\text{MCLR}}$	Any Clock	TRST	—	—	**3**
WDT	Any Clock	TRST	—	—	**3**
Software	Any Clock	TRST	—	—	**3**
Illegal Opcode	Any Clock	TRST	—	—	**3**
Uninitialized W	Any Clock	TRST	—	—	**3**
Trap Conflict	Any Clock	TRST	—	—	**3**

Note 1: TPOR = Power-on Reset delay (10 μs nominal).

2: TSTARTUP = Conditional POR delay of 20 μs nominal (if on-chip regulator is enabled) or 64 ms nominal Power-up Timer delay (if regulator is disabled). TSTARTUP is also applied to all returns from powered-down states, including waking from Sleep mode, only if the regulator is enabled.

3: TRST = Internal state Reset time (20 μs nominal).

4: TOST = Oscillator Start-up Timer. A 10-bit counter counts 1024 oscillator periods before releasing the oscillator clock to the system.

5: TLOCK = PLL lock time (20 μs nominal).

6: TFSCM = Fail-Safe Clock Monitor delay (100 μs nominal).

6.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) have a relatively long start-up time. Therefore, one or more of the following conditions is possible after $\overline{\text{SYSRST}}$ is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

6.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it begins to monitor the system clock source when $\overline{\text{SYSRST}}$ is released. If a valid clock source is not available at this time, the device automatically switches to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine.

6.2.2.1 FSCM Delay for Crystal and PLL Clock Sources

When the system clock source is provided by a crystal oscillator and/or the PLL, a small delay, TFSCM, is automatically inserted after the POR and PWRT delay times. The FSCM does not begin to monitor the system clock source until this delay expires. The FSCM delay time is nominally 500 μs and provides additional time for the oscillator and/or PLL to stabilize. In most cases, the FSCM delay prevents an oscillator failure trap at a device Reset when the PWRT is disabled.

6.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset, with the exception of two registers. The Reset value for the Reset Control register, RCON, depends on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, depends on the type of Reset and the programmed values of the oscillator Configuration bits in the FOSC Configuration register.

REGISTER 7-8: IFS3: INTERRUPT FLAG STATUS REGISTER 3

U-0	U-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0
—	—	DMA5IF	DCIIF	DCIEIF	—	—	C2IF
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
C2RXIF	INT4IF	INT3IF	T9IF	T8IF	MI2C2IF	SI2C2IF	T7IF
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13 **DMA5IF:** DMA Channel 5 Data Transfer Complete Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 12 **DCIIF:** DCI Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 11 **DCIEIF:** DCI Error Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 10-9 **Unimplemented:** Read as '0'

bit 8 **C2IF:** ECAN2 Event Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 7 **C2RXIF:** ECAN2 Receive Data Ready Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 6 **INT4IF:** External Interrupt 4 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 5 **INT3IF:** External Interrupt 3 Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 4 **T9IF:** Timer9 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 3 **T8IF:** Timer8 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 2 **MI2C2IF:** I2C2 Master Events Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 1 **SI2C2IF:** I2C2 Slave Events Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

bit 0 **T7IF:** Timer7 Interrupt Flag Status bit
1 = Interrupt request has occurred
0 = Interrupt request has not occurred

REGISTER 7-11: IEC1: INTERRUPT ENABLE CONTROL REGISTER 1

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
U2TXIE	U2RXIE	INT2IE	T5IE	T4IE	OC4IE	OC3IE	DMA2IE
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
IC8IE	IC7IE	AD2IE	INT1IE	CNIE	—	MI2C1IE	SI2C1IE
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **U2TXIE:** UART2 Transmitter Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 14 **U2RXIE:** UART2 Receiver Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 13 **INT2IE:** External Interrupt 2 Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 12 **T5IE:** Timer5 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 11 **T4IE:** Timer4 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 10 **OC4IE:** Output Compare Channel 4 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 9 **OC3IE:** Output Compare Channel 3 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 8 **DMA2IE:** DMA Channel 2 Data Transfer Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 7 **IC8IE:** Input Capture Channel 8 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 6 **IC7IE:** Input Capture Channel 7 Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 5 **AD2IE:** ADC2 Conversion Complete Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 4 **INT1IE:** External Interrupt 1 Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

REGISTER 16-2: SPIxCON1: SPIx CONTROL REGISTER 1 (CONTINUED)

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)(2)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
•
•
•
000 = Secondary prescale 8:1

bit 1-0 **PPRE<1:0>:** Primary Prescale bits (Master mode)(2)
11 = Primary prescale 1:1
10 = Primary prescale 4:1
01 = Primary prescale 16:1
00 = Primary prescale 64:1

Note 1: The CKE bit is not used in the Framed SPI modes. The user should program this bit to '0' for the Framed SPI modes (FRMEN = 1).

2: Do not set both Primary and Secondary prescalers to a value of 1:1.

3: This bit must be cleared when FRMEN = 1.

REGISTER 19-11: CiFEN1: ECAN™ ACCEPTANCE FILTER ENABLE REGISTER

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN15	FLTEN14	FLTEN13	FLTEN12	FLTEN11	FLTEN10	FLTEN9	FLTEN8
bit 15							bit 8

R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
FLTEN7	FLTEN6	FLTEN5	FLTEN4	FLTEN3	FLTEN2	FLTEN1	FLTEN0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-0 **FLTENn:** Enable Filter n to Accept Messages bits

1 = Enable Filter n

0 = Disable Filter n

REGISTER 19-13: CiBUFPNT2: ECAN™ FILTER 4-7 BUFFER POINTER REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F7BP<3:0>				F6BP<3:0>			
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
F5BP<3:0>				F4BP<3:0>			
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **F7BP<3:0>:** RX Buffer Written when Filter 7 Hits bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 11-8 **F6BP<3:0>:** RX Buffer Written when Filter 6 Hits bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 7-4 **F5BP<3:0>:** RX Buffer Written when Filter 5 Hits bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

bit 3-0 **F4BP<3:0>:** RX Buffer Written when Filter 4 Hits bits
1111 = Filter hits received in RX FIFO buffer
1110 = Filter hits received in RX Buffer 14
•
•
•
0001 = Filter hits received in RX Buffer 1
0000 = Filter hits received in RX Buffer 0

REGISTER 21-2: ADxCON2: ADCx CONTROL REGISTER 2 (where x = 1 or 2)

R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0
VCFG<2:0>			—	—	CSCNA	CHPS<1:0>	
bit 15							bit 8

R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
BUFS	—	SMPI<3:0>				BUFM	ALTS
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **VCFG<2:0>:** Converter Voltage Reference Configuration bits

	VREF+	VREF-
000	AVDD	AVSS
001	External VREF+	AVSS
010	AVDD	External VREF-
011	External VREF+	External VREF-
1xx	AVDD	Avss

bit 12-11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Scan Input Selections for CH0+ during Sample A bit
1 = Scan inputs
0 = Do not scan inputs

bit 9-8 **CHPS<1:0>:** Selects Channels Utilized bits
When AD12B = 1, CHPS<1:0> is: U-0, Unimplemented, Read as '0'
1x = Converts CH0, CH1, CH2 and CH3
01 = Converts CH0 and CH1
00 = Converts CH0

bit 7 **BUFS:** Buffer Fill Status bit (only valid when BUFM = 1)
1 = ADC is currently filling second half of buffer, user should access data in first half
0 = ADC is currently filling first half of buffer, user should access data in second half

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **SMPI<3:0>:** Selects Increment Rate for DMA Addresses bits or number of sample/conversion operations per interrupt
1111 = Increments the DMA address or generates interrupt after completion of every 16th sample/conversion operation
1110 = Increments the DMA address or generates interrupt after completion of every 15th sample/conversion operation
•
•
•
0001 = Increments the DMA address or generates interrupt after completion of every 2nd sample/conversion operation
0000 = Increments the DMA address or generates interrupt after completion of every sample/conversion operation

bit 1 **BUFM:** Buffer Fill Mode Select bit
1 = Starts filling first half of buffer on first interrupt and second half of the buffer on next interrupt
0 = Always starts filling buffer from the beginning

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses channel input selects for Sample A on first sample and Sample B on next sample
0 = Always uses channel input selects for Sample A

22.4 Watchdog Timer (WDT)

For dsPIC33FJXXXGPX06A/X08A/X10A devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

The nominal WDT clock source from LPRC is 32 kHz. This feeds a prescaler and then can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the WDTPRE Configuration bit. With a 32 kHz input, the prescaler yields a nominal WDT time-out period (TWDT) of 1 ms in 5-bit mode, or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the WDTPOST<3:0> Configuration bits (FWDT<3:0>) which allow the selection of a total of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler, time-out periods ranging from 1 ms to 131 seconds can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSC bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a PWRSAV instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a CLRWDT instruction during normal execution

If the WDT is enabled, it will continue to run during Sleep or Idle modes. When the WDT time-out occurs, the device will wake the device and code execution will continue from where the PWRSAV instruction was executed. The corresponding SLEEP or IDLE bits (RCON<3,2>) will need to be cleared in software after the device wakes up.

The WDT flag bit, WDTO (RCON<4>), is not automatically cleared following a WDT time-out. To detect subsequent WDT events, the flag must be cleared in software.

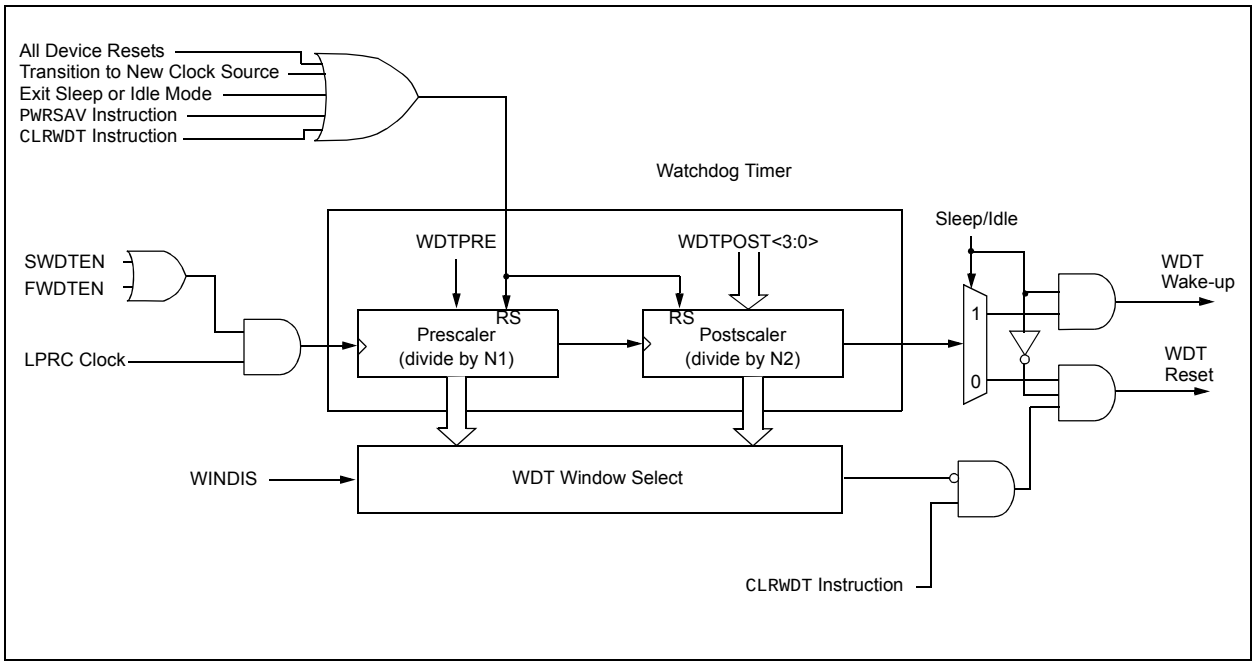
Note:	The CLRWDT and PWRSAV instructions clear the prescaler and postscaler counts when executed.

The WDT is enabled or disabled by the FWDTEN Configuration bit in the FWDT Configuration register. When the FWDTEN Configuration bit is set, the WDT is always enabled.

The WDT can be optionally controlled in software when the FWDTEN Configuration bit has been programmed to '0'. The WDT is enabled in software by setting the SWDTEN control bit (RCON<5>). The SWDTEN control bit is cleared on any device Reset. The software WDT option allows the user to enable the WDT for critical code segments and disable the WDT during non-critical segments for maximum power savings.

Note:	If the WINDIS bit (FWDT<6>) is cleared, the CLRWDT instruction should be executed by the application software only during the last 1/4 of the WDT period. This CLRWDT window can be determined by using a timer. If a CLRWDT instruction is executed before this window, a WDT Reset occurs.

FIGURE 22-2: WDT BLOCK DIAGRAM



24.7 MPLAB SIM Software Simulator

The MPLAB SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC® DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB SIM Software Simulator fully supports symbolic debugging using the MPLAB C Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

24.8 MPLAB REAL ICE In-Circuit Emulator System

MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs PIC® Flash MCUs and dsPIC® Flash DSCs with the easy-to-use, powerful graphical user interface of the MPLAB Integrated Development Environment (IDE), included with each kit.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB IDE. In upcoming releases of MPLAB IDE, new devices will be supported, and new features will be added. MPLAB REAL ICE offers significant advantages over competitive emulators including low-cost, full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, a ruggedized probe interface and long (up to three meters) interconnection cables.

24.9 MPLAB ICD 3 In-Circuit Debugger System

MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost effective high-speed hardware debugger/programmer for Microchip Flash Digital Signal Controller (DSC) and microcontroller (MCU) devices. It debugs and programs PIC® Flash microcontrollers and dsPIC® DSCs with the powerful, yet easy-to-use graphical user interface of MPLAB Integrated Development Environment (IDE).

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

24.10 PICkit 3 In-Circuit Debugger/ Programmer and PICkit 3 Debug Express

The MPLAB PICkit 3 allows debugging and programming of PIC® and dsPIC® Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB Integrated Development Environment (IDE). The MPLAB PICkit 3 is connected to the design engineer's PC using a full speed USB interface and can be connected to the target via an Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the reset line to implement in-circuit debugging and In-Circuit Serial Programming™.

The PICkit 3 Debug Express include the PICkit 3, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

TABLE 25-9: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS (CONTINUED)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
DI60a	IICL	**Input Low Injection Current**	0	—	-5(5,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, and RB11
DI60b	IICH	**Input High Injection Current**	0	—	+5(6,7,8)	mA	All pins except VDD, VSS, AVDD, AVSS, MCLR, VCAP, SOSCI, SOSCO, RB11, and all 5V tolerant pins(7)
DI60c	∑ IICT	**Total Input Injection Current (sum of all I/O and control pins)**	-20(9)	—	+20(9)	mA	Absolute instantaneous sum of all ± input injection currents from all I/O pins (| IICL + | IICH |) ≤ ∑ IICT

Note 1: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated.

2: The leakage current on the MCLR pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

4: See **"Pin Diagrams"** for a list of 5V tolerant pins.

5: VIL source < (VSS – 0.3). Characterized but not tested.

6: Non-5V tolerant pins VIH source > (VDD + 0.3), 5V tolerant pins VIH source > 5.5V. Characterized but not tested.

7: Digital 5V tolerant pins cannot tolerate any "positive" input injection current from input sources > 5.5V.

8: Injection currents > | 0 | can affect the ADC results by approximately 4-6 counts.

9: Any number and/or combination of I/O pins not excluded under IICL or IICH conditions are permitted provided the mathematical "absolute instantaneous" sum of the input injection currents from all pins do not exceed the specified limit. Characterized but not tested.

TABLE 25-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
DO10	VOL	**Output Low Voltage** I/O Pins: 2x Sink Driver Pins - All pins not defined by 4x or 8x driver pins	—	—	0.4	V	IOL ≤ 3 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 4x Sink Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	—	—	0.4	V	IOL ≤ 6 mA, VDD = 3.3V
		Output Low Voltage I/O Pins: 8x Sink Driver Pins - OSC2, CLKO, RC15	—	—	0.4	V	IOL ≤ 10 mA, VDD = 3.3V
DO20	VOH	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	2.4	—	—	V	IOL ≥ -3 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	2.4	—	—	V	IOL ≥ -6 mA, VDD = 3.3V
		Output High Voltage I/O Pins: 8x Source Driver Pins - OSC2, CLKO, RC15	2.4	—	—	V	IOL ≥ -10 mA, VDD = 3.3V
DO20A	VOH1	**Output High Voltage** I/O Pins: 2x Source Driver Pins - All pins not defined by 4x or 8x driver pins	1.5	—	—	V	IOH ≥ -6 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -5 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -2 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 4x Source Driver Pins - RA2, RA3, RA9, RA10, RA14, RA15, RB0, RB1, RB11, RF4, RF5, RG2, RG3	1.5	—	—	V	IOH ≥ -12 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -11 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -3 mA, VDD = 3.3V See **Note 1**
		Output High Voltage 8x Source Driver Pins - OSC2, CLKO, RC15	1.5	—	—	V	IOH ≥ -16 mA, VDD = 3.3V See **Note 1**
			2.0	—	—		IOH ≥ -12 mA, VDD = 3.3V See **Note 1**
			3.0	—	—		IOH ≥ -4 mA, VDD = 3.3V See **Note 1**

Note 1: Parameters are characterized, but not tested.

TABLE 25-36: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

AC CHARACTERISTICS				Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C -40°C ≤ TA ≤ +125°C for Extended			
Param No.	Symbol	Characteristic		Min(1)	Max	Units	Conditions
IM10	TLO:SCL	Clock Low Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM11	THI:SCL	Clock High Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	—
IM20	TF:SCL	SDAx and SCLx Fall Time	100 kHz mode	—	300	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	100	ns	
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode(2)	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode(2)	40	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	µs	—
			400 kHz mode	0	0.9	µs	
			1 MHz mode(2)	0.2	—	µs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	Only relevant for Repeated Start condition
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	After this period the first clock pulse is generated
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TCY/2 (BRG + 1)	—	µs	—
			400 kHz mode	TCY/2 (BRG + 1)	—	µs	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	µs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TCY/2 (BRG + 1)	—	ns	—
			400 kHz mode	TCY/2 (BRG + 1)	—	ns	
			1 MHz mode(2)	TCY/2 (BRG + 1)	—	ns	
IM40	TAA:SCL	Output Valid From Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode(2)	—	400	ns	—

Note 1: BRG is the value of the I^2C Baud Rate Generator. Refer to **Section 19. "Inter-Integrated Circuit™ (I^2C™)"** (DS70195) in the "*dsPIC33F/PIC24H Family Reference Manual*".

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: Typical value for this parameter is 130 ns.

26.0 HIGH TEMPERATURE ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33FJXXXGPX06A/X08A/X10A electrical characteristics for devices operating in an ambient temperature range of -40°C to +150°C.

The specifications between -40°C to +150°C are identical to those shown in **Section 25.0 "Electrical Characteristics"** for operation between -40°C to +125°C, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter DC10 in **Section 25.0 "Electrical Characteristics"** is the Industrial and Extended temperature equivalent of HDC10.

Absolute maximum ratings for the dsPIC33FJXXXGPX06A/X08A/X10A high temperature devices are listed below. Exposure to these maximum rating conditions for extended periods can affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings

(See Note 1)

Ambient temperature under bias**(4)** ..... -40°C to +150°C
Storage temperature ..... -65°C to +160°C
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant with respect to V_{SS}**(5)** ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when V_{DD} < 3.0V**(5)** ..... -0.3V to (V_{DD} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DD} \geq$ 3.0V**(5)** ..... -0.3V to 5.6V
Voltage on V_{CAP} with respect to V_{SS} ..... 2.25V to 2.75V
Maximum current out of V_{SS} pin ..... 60 mA
Maximum current into V_{DD} pin**(2)** ..... 60 mA
Maximum junction temperature ..... +155°C
Maximum current sourced/sunk by any 2x I/O pin**(3)** ..... 2 mA
Maximum current sourced/sunk by any 4x I/O pin**(3)** ..... 4 mA
Maximum current sourced/sunk by any 8x I/O pin**(3)** ..... 8 mA
Maximum current sunk by all ports combined ..... 10 mA
Maximum current sourced by all ports combined**(2)** ..... 10 mA

Note 1: Stresses above those listed under "Absolute Maximum Ratings" can cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods can affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 26-2).

3: Unlike devices at 125°C and below, the specifications in this section also apply to the CLKOUT, V_{REF+}, V_{REF-}, SCLx, SDAx, PGECx, and PGEDx pins.

4: AEC-Q100 reliability testing for devices intended to operate at 150°C is 1,000 hours. Any design in which the total operating time from 125°C to 150°C will be greater than 1,000 hours is not warranted without prior written approval from Microchip Technology Inc.

5: Refer to the **"Pin Diagrams"** section for 5V tolerant pins.

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature			
Parameter No.	**Typical**	**Max**	**Units**	**Conditions**		
Power-Down Current (IPD)						
HDC61c	3	5	μA	+150°C	3.3V	Watchdog Timer Current: ΔIWDT(2,4)

Note 1: Base IPD is measured with all peripherals and clocks shut down. All I/Os are configured as inputs and pulled to VSS. WDT, etc., are all switched off, and VREGS (RCON<8>) = 1.

2: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.

3: These currents are measured on the device containing the most memory in this family.

4: These parameters are characterized, but are not tested in manufacturing.

TABLE 26-5: DC CHARACTERISTICS: DOZE CURRENT (IDOZE)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature				
Parameter No.	**Typical(1)**	**Max**	**Doze Ratio**	**Units**	**Conditions**		
HDC72a	39	45	1:2	mA	+150°C	3.3V	20 MIPS
HDC72f	18	25	1:64	mA			
HDC72g	18	25	1:128	mA			

Note 1: Parameters with Doze ratios of 1:2 and 1:64 are characterized, but are not tested in manufacturing.

26.2 AC Characteristics and Timing Parameters

The information contained in this section defines dsPIC33FJXXXGPX06A/X08A/X10A AC characteristics and timing parameters for high temperature devices. However, all AC timing specifications in this section are the same as those in **Section 25.2 "AC Characteristics and Timing Parameters"**, with the exception of the parameters listed in this section.

Parameters in this section begin with an H, which denotes High temperature. For example, parameter OS53 in **Section 25.2 "AC Characteristics and Timing Parameters"** is the Industrial and Extended temperature equivalent of HOS53.

TABLE 26-7: TEMPERATURE AND VOLTAGE SPECIFICATIONS – AC

AC CHARACTERISTICS	**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature Operating voltage VDD range as described in Table 26-1.

FIGURE 26-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

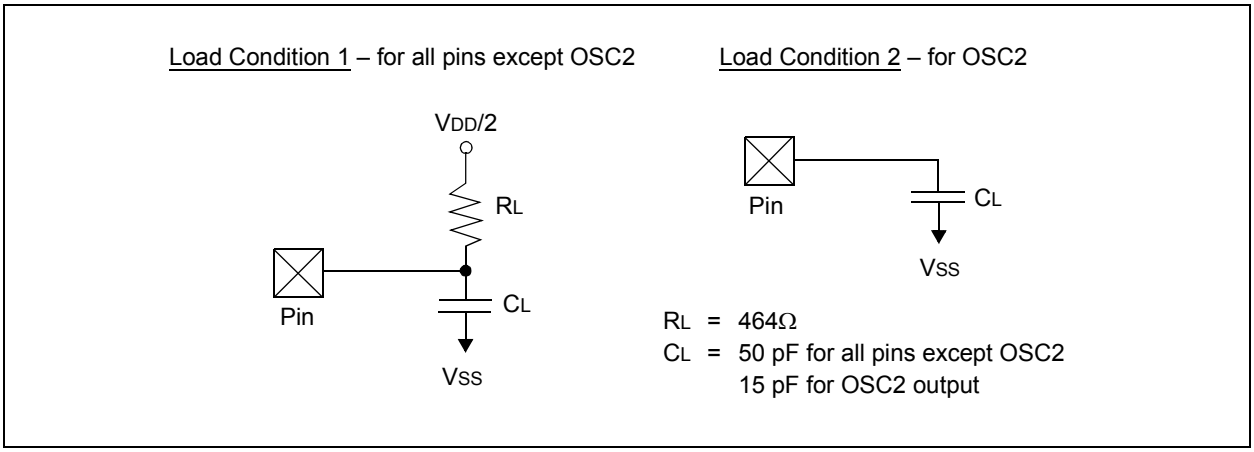


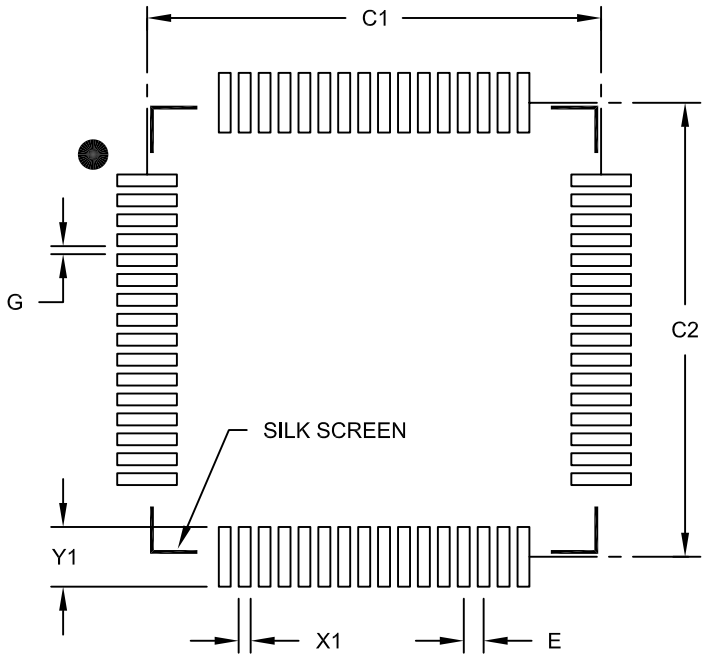
TABLE 26-8: PLL CLOCK TIMING SPECIFICATIONS

AC CHARACTERISTICS		**Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HOS53	DCLK	CLKO Stability (Jitter)(1)	-5	0.5	5	%	Measured over 100 ms period

Note 1: These parameters are characterized, but are not tested in manufacturing.

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B